

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (U-MOS II)

# 2SK2985

HIGH CURRENT SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

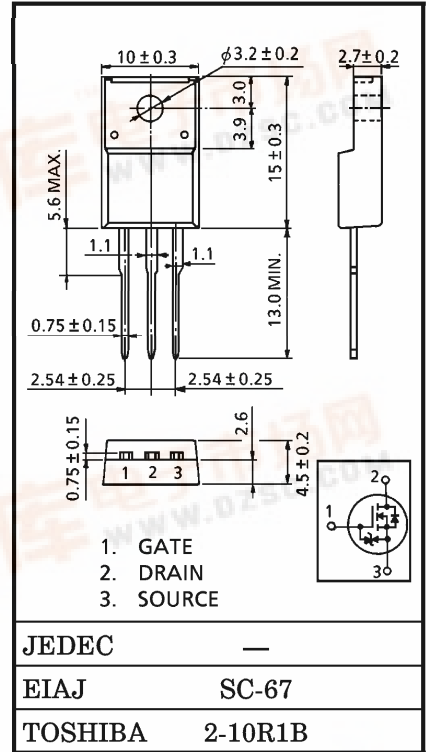
INDUSTRIAL APPLICATIONS

Unit in mm

- Low Drain-Source ON Resistance :  $R_{DS(ON)} = 4.5 \text{ m}\Omega$  (Typ.)
- High Forward Transfer Admittance :  $|Y_{fs}| = 70 \text{ S}$  (Typ.)
- Low Leakage Current :  $I_{DSS} = 100 \mu\text{A}$  (Max.) ( $V_{DS} = 60 \text{ V}$ )
- Enhancement-Mode :  $V_{th} = 1.3 \sim 2.5 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$V_{DSS}$	60	V
Drain-Gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	$V_{DGR}$	60	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current	DC	$I_D$	45
	Pulse	$I_{DP}$	180
Drain Power Dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	45	W
Single Pulse Avalanche Energy**	$E_{AS}$	701	mJ
Avalanche Current	$I_{AR}$	45	A
Repetitive Avalanche Energy*	$E_{AR}$	4.5	mJ
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-55 \sim 150$	$^\circ\text{C}$



Weight 1.9 g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	2.78	$^\circ\text{C/W}$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	62.5	$^\circ\text{C/W}$

Note ;

\* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

\*\*  $V_{DD} = 25 \text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 471 \mu\text{H}$ ,  $I_{AR} = 45 \text{ A}$ ,  $R_G = 25 \Omega$

This transistor is an electrostatic sensitive device.

Please handle with caution.

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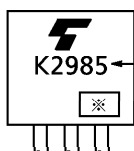
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	—	—	±10	μA	
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	—	—	100	μA	
Drain-Source Breakdown Voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	—	—	V	
	V <sub>(BR) DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	40	—	—		
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.3	—	2.5	V	
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A	—	4.5	5.8	mΩ	
		V <sub>GS</sub> = 4 V, I <sub>D</sub> = 25 A	—	5.8	10		
Forward Transfer Admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A	35	70	—	S	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	—	9300	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>		—	910	—		
Output Capacitance	C <sub>oss</sub>		—	1435	—		
Switching Time	Rise Time	t <sub>r</sub>		—	18	—	ns
	Turn-on Time	t <sub>on</sub>		—	50	—	
	Fall Time	t <sub>f</sub>		—	110	—	
	Turn-off Time	t <sub>off</sub>		V <sub>IN</sub> : t <sub>r</sub> , t <sub>f</sub> < 5 ns Duty ≤ 1%, t <sub>w</sub> = 10 μs	—	480	
Total Gate Charge (Gate-Source Plus Gate-Drain)	Q <sub>g</sub>	V <sub>DD</sub> ≐ 48 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 45 A	—	210	—	nC	
Gate-Source Charge	Q <sub>gs</sub>		—	145	—		
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>		—	65	—		

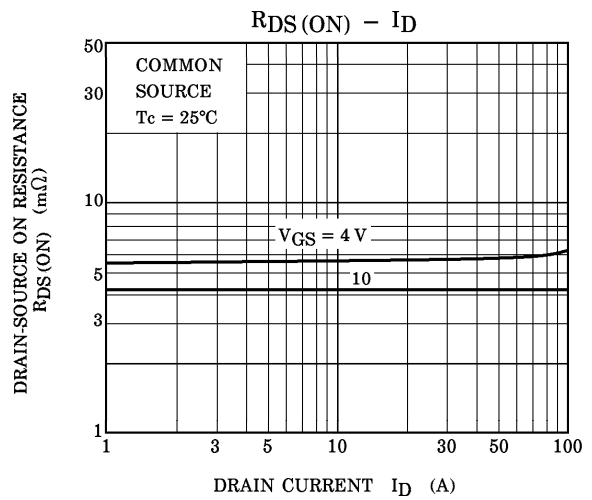
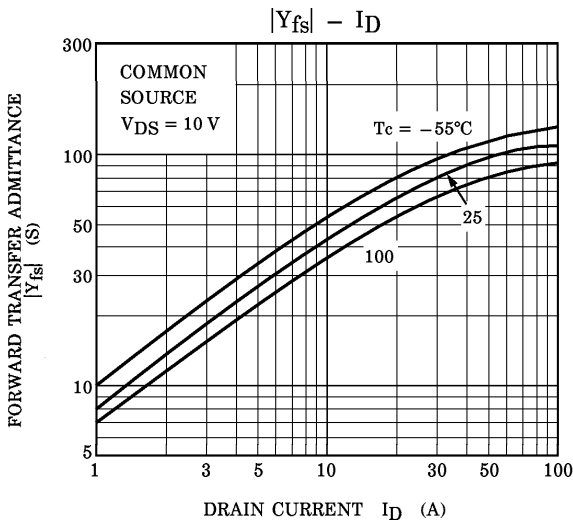
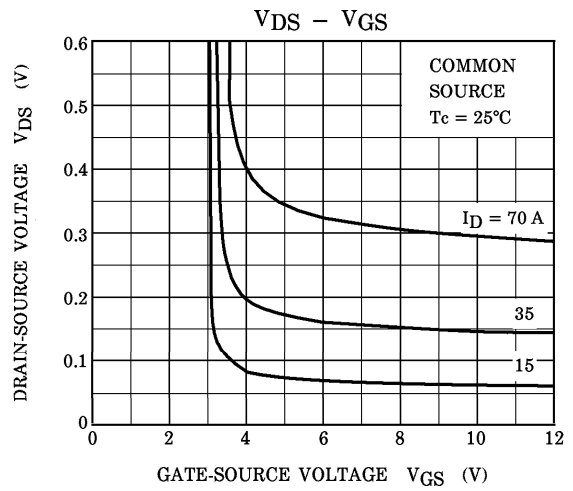
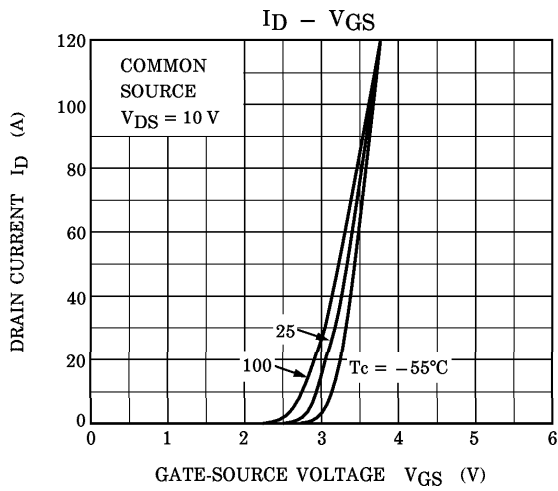
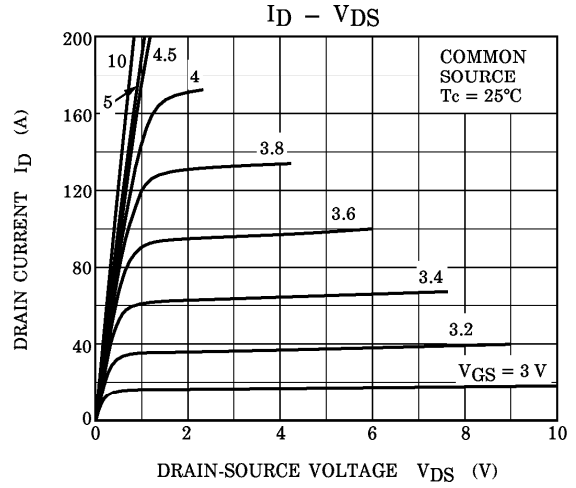
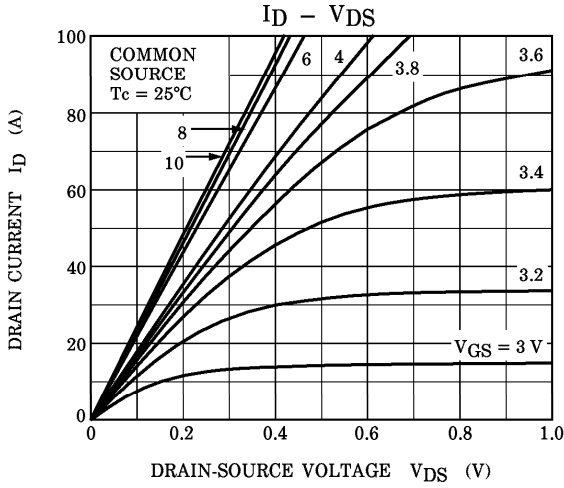
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

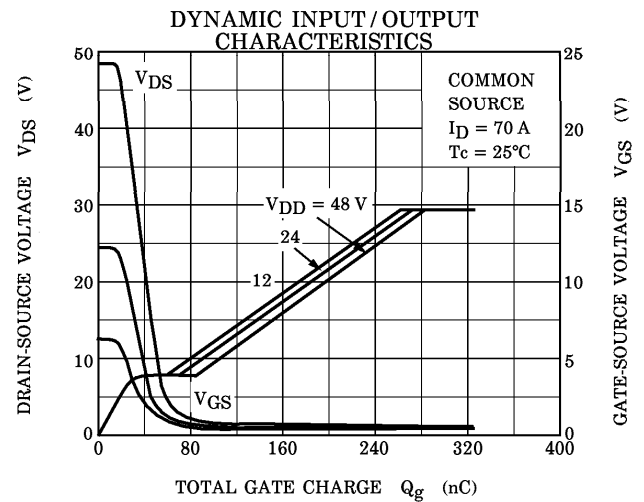
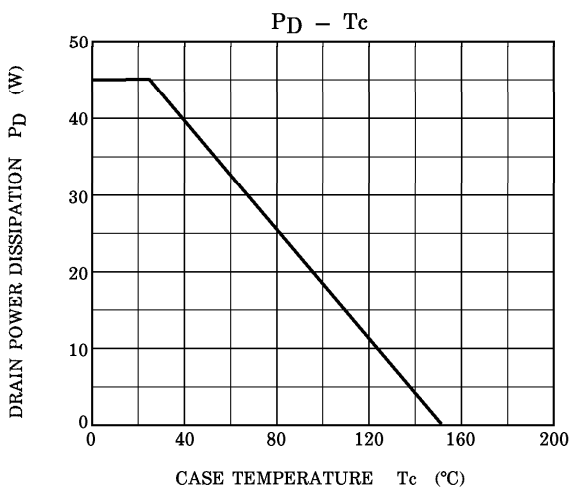
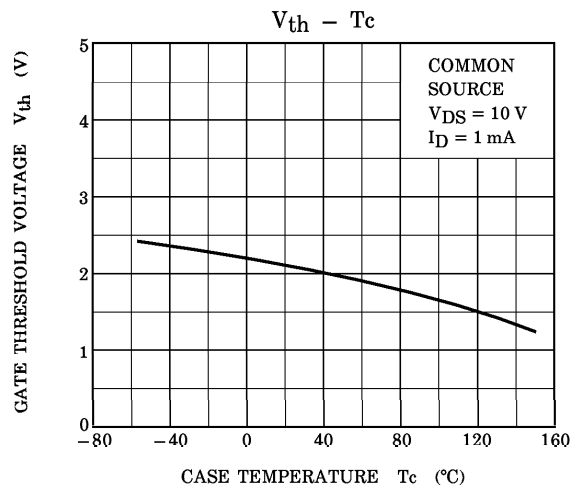
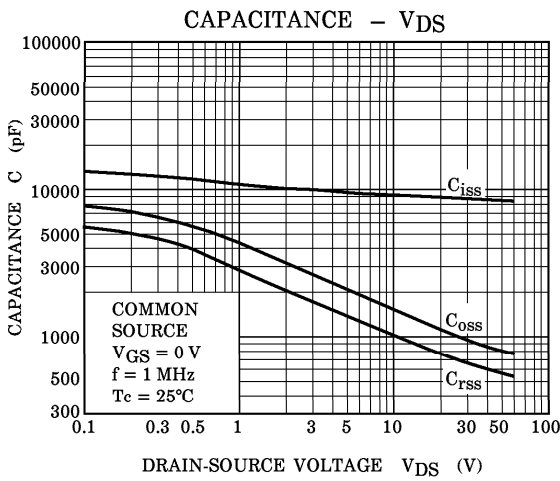
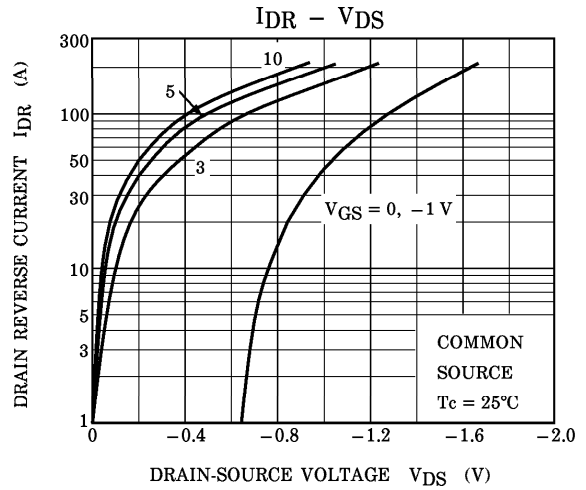
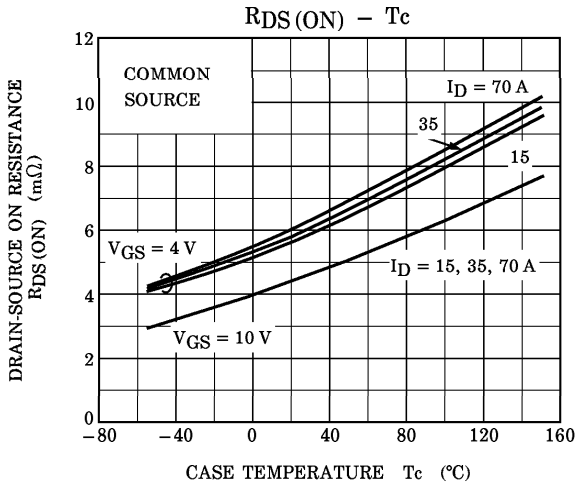
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I <sub>DR</sub>	—	—	—	45	A
Pulse Drain Reverse Current	I <sub>DRP</sub>	—	—	—	180	A
Diode Forward Voltage	V <sub>DSSF</sub>	I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V	—	—	-1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>DR</sub> = 45 A, V <sub>GS</sub> = 0 V	—	60	—	ns
Reverse Recovery Charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 A / μs	—	50	—	nC

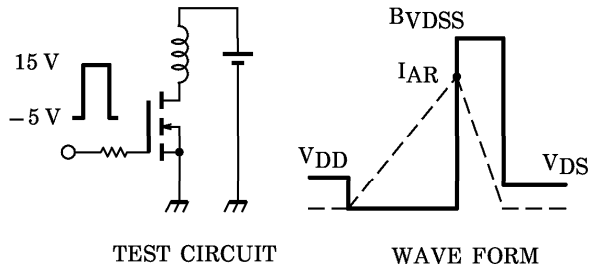
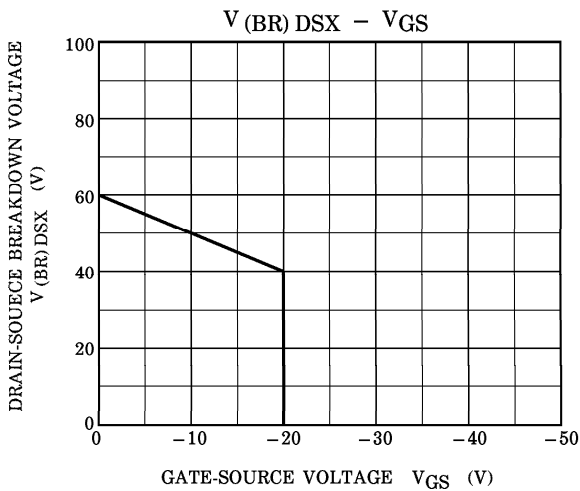
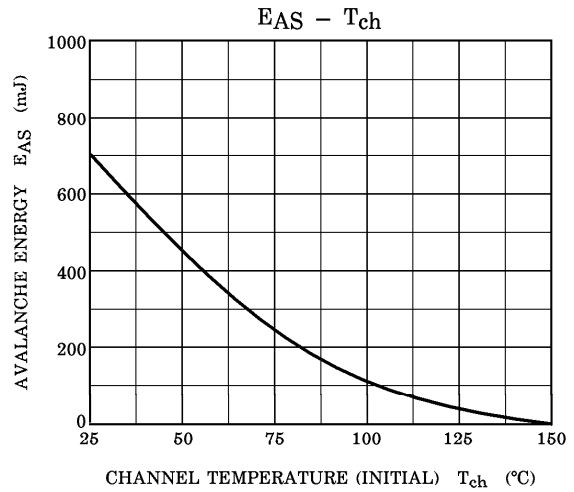
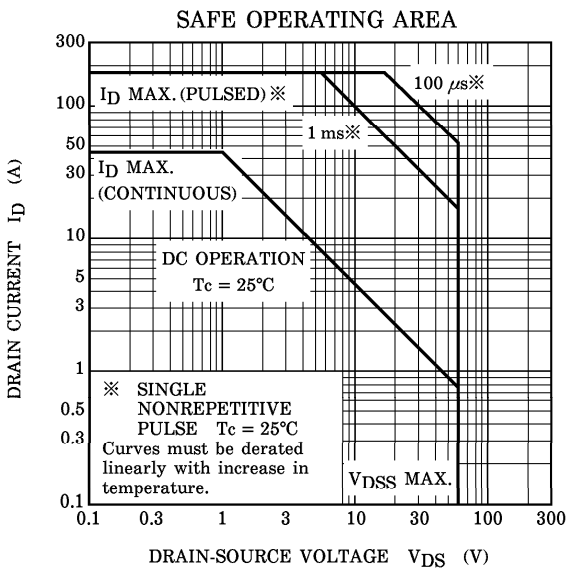
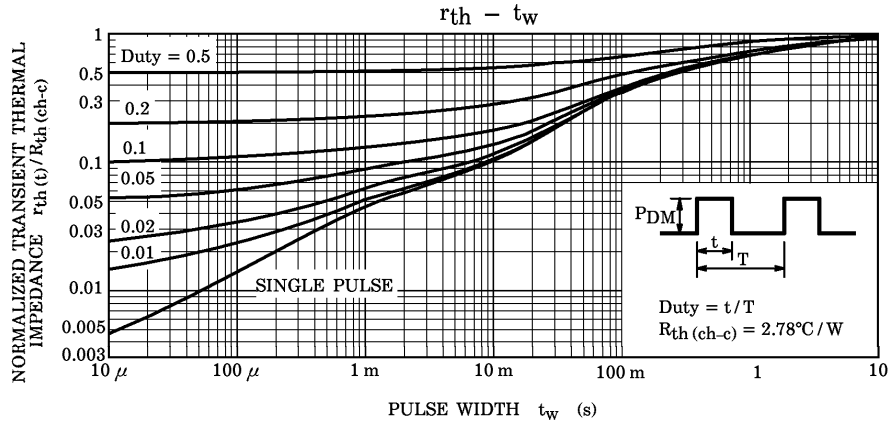
MARKING



TYPE → K2985  
 ※ Lot Number  
 □ □ → Month (Starting from Alphabet A)  
 ———— → Year (Last Number of the Christian Era)







Peak  $I_{AR} = 45$  A,  $R_G = 25 \Omega$   $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BV_{DSS}}{BV_{DSS} - V_{DD}} \right)$   
 $V_{DD} = 25$  V,  $L = 471 \mu H$